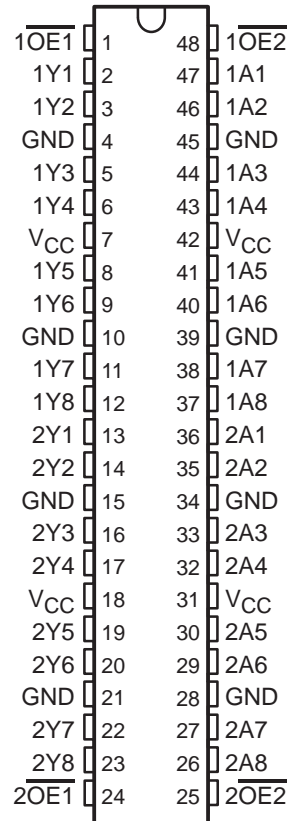


SN54LVTH16541, SN74LVTH16541 3.3-V ABT 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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- Members of the Texas Instruments *Widebus™* Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54LVTH16541 . . . WD PACKAGE
SN74LVTH16541 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

These 16-bit buffers/drivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

These devices are noninverting 16-bit buffers composed of two 8-bit sections with separate output-enable signals. For either 8-bit buffer section, the two output-enable ($1OE1$ and $1OE2$ or $2OE1$ and $2OE2$) inputs must be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 8-bit buffer section are in the high-impedance state.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.



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**TEXAS
INSTRUMENTS**

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3.3-V ABT 16-BIT BUFFERS/DRIVERS
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description (continued)

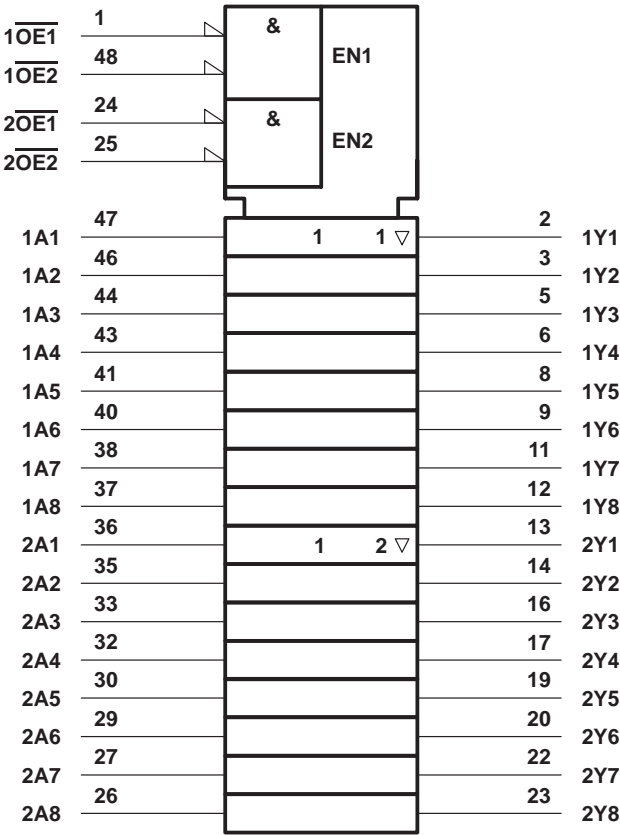
These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16541 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74LVTH16541 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each 8-bit section)

INPUTS			OUTPUT Y
$\overline{\text{OE1}}$	$\overline{\text{OE2}}$	A	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

logic symbol†

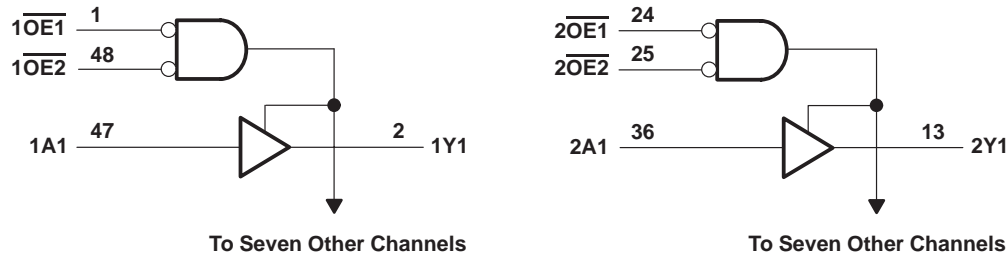


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SN54LVTH16541, SN74LVTH16541 3.3-V ABT 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O : SN54LVTH16541	96 mA
SN74LVTH16541	128 mA
Current into any output in the high state, I_O (see Note 2): SN54LVTH16541	48 mA
SN74LVTH16541	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 3): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

		SN54LVTH16541		SN74LVTH16541		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage		5.5		5.5	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54LVTH16541			SN74LVTH16541			UNIT	
				MIN	TYP†	MAX	MIN	TYP†	MAX		
V _{IK}		V _{CC} = 2.7 V, I _I = −18 mA		−1.2			−1.2			V	
V _{OH}		V _{CC} = 2.7 V to 3.6 V, I _{OH} = −100 μA		V _{CC} −0.2			V _{CC} −0.2			V	
		V _{CC} = 2.7 V, I _{OH} = −8 mA		2.4			2.4				
		V _{CC} = 3 V	I _{OH} = −24 mA	2							
			I _{OH} = −32 mA				2				
V _{OL}		V _{CC} = 2.7 V	I _{OL} = 100 μA	0.2			0.2			V	
			I _{OL} = 24 mA	0.5			0.5				
		V _{CC} = 3 V	I _{OL} = 16 mA	0.4			0.4				
			I _{OL} = 32 mA	0.5			0.5				
			I _{OL} = 48 mA	0.55							
			I _{OL} = 64 mA				0.55				
I _I		V _{CC} = 0 or 3.6 V, V _I = 5.5 V		10			10			μA	
	Control inputs	V _{CC} = 3.6 V, V _I = V _{CC} or GND		±1			±1				
	Data inputs	V _{CC} = 3.6 V	V _I = V _{CC}	1			1				
			V _I = 0	−5			−5				
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V					±100			μA	
I _I (hold)	Data inputs	V _{CC} = 3 V	V _I = 0.8 V	75			75			μA	
			V _I = 2 V	−75			−75				
		V _{CC} = 3.6 V [‡] , V _I = 0 to 3.6 V					500 −750				
I _{OZH}		V _{CC} = 3.6 V, V _O = 3 V		5			5			μA	
I _{OZL}		V _{CC} = 3.6 V, V _O = 0.5 V		−5			−5			μA	
I _{OZPU}		V _{CC} = 0 to 1.5 V, V _O = 0.5 V to 3 V, OE = don't care		±100*			±100			μA	
I _{OZPD}		V _{CC} = 1.5 V to 0, V _O = 0.5 V to 3 V, OE = don't care		±100*			±100			μA	
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND	Outputs high		0.19			0.19			mA
			Outputs low		5			5			
			Outputs disabled		0.19			0.19			
ΔI _{CC} [§]		V _{CC} = 3 V to 3.6 V, One input at V _{CC} − 0.6 V, Other inputs at V _{CC} or GND		0.2			0.2			mA	
C _i		V _I = 3 V or 0		4			4			pF	
C _O		V _O = 3 V or 0		9			9			pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than $V_{CC}\text{ or GND}$.

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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH16541				SN74LVTH16541				UNIT	
			$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$			
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN		MAX
t _{PLH}	A	Y	1	3.7		4	1	2.4	3.5		3.8	ns
t _{PHL}			1	3.7		4	1	2	3.5		3.8	
t _{PZH}	\overline{OE}	Y	1.1	4.8		5.7	1.2	2.7	4.6		5.5	ns
t _{PZL}			1.1	4.8		5.4	1.2	2.8	4.6		5.2	
t _{PHZ}	\overline{OE}	Y	2.1	6.2		6.5	2.2	4.1	5.9		6.2	ns
t _{PLZ}			1.9	5.7		6	2.2	3.8	5.4		5.5	
t _{sk(o)}									0.5		0.5	ns

† All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^\circ\text{C}$.

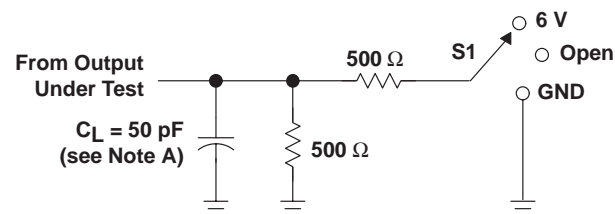
SN54LVTH16541, SN74LVTH16541

3.3-V ABT 16-BIT BUFFERS/DRIVERS

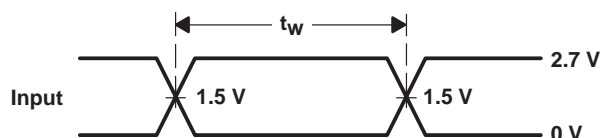
WITH 3-STATE OUTPUTS

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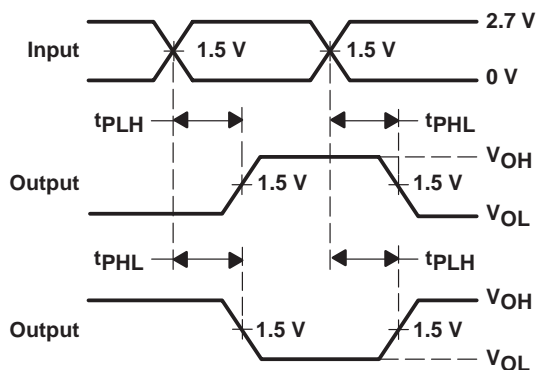
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

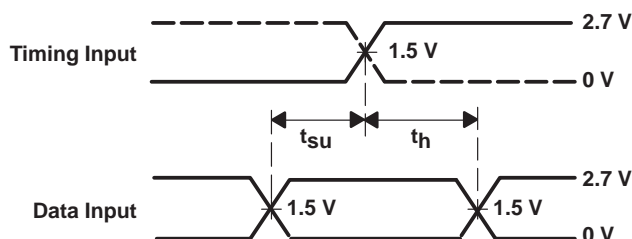


VOLTAGE WAVEFORMS
PULSE DURATION

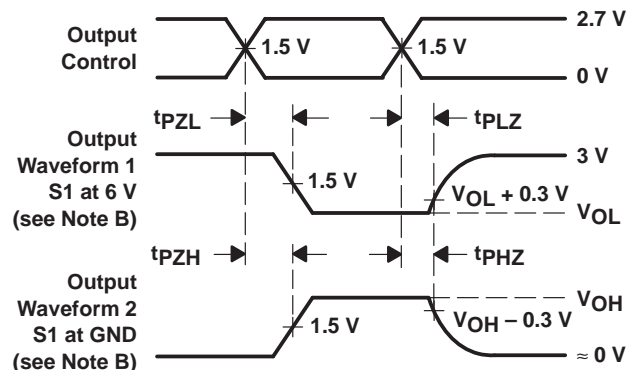


VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PHZ}	GND



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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